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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	4964
Number of Logic Elements/Cells	118143
Total RAM Bits	8315904
Number of I/O	260
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	572-BGA, FCBGA
Supplier Device Package	572-FBGA, FC (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx125df25i3n

I/O Pin Leakage Current

Table 1-7 lists the Arria II GX I/O pin leakage current specifications.

Table 1-7. I/O Pin Leakage Current for Arria II GX Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0 \text{ V to } V_{CCIO MAX}$	-10	—	10	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO MAX}$	-10	—	10	μA

Table 1-8 lists the Arria II GZ I/O pin leakage current specifications.

Table 1-8. I/O Pin Leakage Current for Arria II GZ Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0 \text{ V to } V_{CCIO MAX}$	-20	—	20	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO MAX}$	-20	—	20	μA

Bus Hold

Bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-9 lists bus hold specifications for Arria II GX devices.

Table 1-9. Bus Hold Parameters for Arria II GX Devices (Note 1)

Parameter	Symbol	Cond.	$V_{CCIO} (\text{V})$												Unit	
			1.2		1.5		1.8		2.5		3.0		3.3			
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Bus-hold low, sustaining current	I_{SUSL}	$V_{IN} > V_{IL} (\text{max.})$	8	—	12	—	30	—	50	—	70	—	70	—	μA	
Bus-hold high, sustaining current	I_{SUSH}	$V_{IN} < V_{IL} (\text{min.})$	-8	—	-12	—	-30	—	-50	—	-70	—	-70	—	μA	
Bus-hold low, overdrive current	I_{ODL}	$0 \text{ V} < V_{IN} < V_{CCIO}$	—	125	—	175	—	200	—	300	—	500	—	500	μA	
Bus-hold high, overdrive current	I_{ODH}	$0 \text{ V} < V_{IN} < V_{CCIO}$	—	-125	—	-175	—	-200	—	-300	—	-500	—	-500	μA	
Bus-hold trip point	V_{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V	

Note to Table 1-9:

- (1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Table 1–17 lists the pin capacitance for Arria II GZ devices.

Table 1–17. Pin Capacitance for Arria II GZ Devices

Symbol	Description	Typical	Unit
C_{IOTB}	Input capacitance on the top and bottom I/O pins	4	pF
C_{IOLR}	Input capacitance on the left and right I/O pins	4	pF
C_{CLKTB}	Input capacitance on the top and bottom non-dedicated clock input pins	4	pF
C_{CLKLR}	Input capacitance on the left and right non-dedicated clock input pins	4	pF
C_{OUTFB}	Input capacitance on the dual-purpose clock output and feedback pins	5	pF
$C_{CLK1}, C_{CLK3}, C_{CLK8},$ <i>and</i> C_{CLK10}	Input capacitance for dedicated clock input pins	2	pF

Internal Weak Pull-Up and Weak Pull-Down Resistors

Table 1–18 lists the weak pull-up and pull-down resistor values for Arria II GX devices.

Table 1–18. Internal Weak Pull-up and Weak Pull-Down Resistors for Arria II GX Devices (Note 1)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R_{PU}	Value of I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	$V_{CCIO} = 3.3 V \pm 5\% \text{ (2)}$	7	25	41	kΩ
		$V_{CCIO} = 3.0 V \pm 5\% \text{ (2)}$	7	28	47	kΩ
		$V_{CCIO} = 2.5 V \pm 5\% \text{ (2)}$	8	35	61	kΩ
		$V_{CCIO} = 1.8 V \pm 5\% \text{ (2)}$	10	57	108	kΩ
		$V_{CCIO} = 1.5 V \pm 5\% \text{ (2)}$	13	82	163	kΩ
		$V_{CCIO} = 1.2 V \pm 5\% \text{ (2)}$	19	143	351	kΩ
R_{PD}	Value of TCK pin pull-down resistor	$V_{CCIO} = 3.3 V \pm 5\%$	6	19	29	kΩ
		$V_{CCIO} = 3.0 V \pm 5\%$	6	22	32	kΩ
		$V_{CCIO} = 2.5 V \pm 5\%$	6	25	42	kΩ
		$V_{CCIO} = 1.8 V \pm 5\%$	7	35	70	kΩ
		$V_{CCIO} = 1.5 V \pm 5\%$	8	50	112	kΩ

Notes to Table 1–18:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.
- (2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V _{CCIO} (V)			V _{IL} (V)		V _{IH} (V)		V _{OL} (V)	V _{OH} (V)	I _{OL} (mA)	I _{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.2 V	1.14	1.2	1.26	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.25 × V _{CCIO}	0.75 × V _{CCIO}	2	-2
3.0-V PCI	2.85	3	3.15	—	0.3 × V _{CCIO}	0.5 × V _{CCIO}	3.6	0.1 × V _{CCIO}	0.9 × V _{CCIO}	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	0.35 × V _{CCIO}	0.5 × V _{CCIO}	—	0.1 × V _{CCIO}	0.9 × V _{CCIO}	1.5	-0.5

Table 1–24 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GX devices.

Table 1–24. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GX Devices

I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	0.48 × V _{CCIO}	0.5 × V _{CCIO}	0.52 × V _{CCIO}	—	V _{CCIO} /2	—

Table 1–25 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GZ devices.

Table 1–25. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GZ Devices

I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}	0.47 × V _{CCIO}	V _{REF}	0.53 × V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V _{CCIO} /2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V _{CCIO} /2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}	—	V _{CCIO} /2	—

Table 1–27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} (mA)	I _{OH} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-15 Class II	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	16	-16
HSTL-18 Class I	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-18 Class II	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-15 Class I	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-15 Class II	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	16	-16

Table 1–28 lists the differential SSTL I/O standards for Arria II GX devices.

Table 1–28. Differential SSTL I/O Standards for Arria II GX Devices

I/O Standard	V _{CCIO} (V)			V _{SWING(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)		V _{OX(AC)} (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V _{CCIO}	V _{CCIO} /2 - 0.2	—	V _{CCIO} /2 + 0.2	0.7	V _{CCIO}	V _{CCIO} /2 - 0.15	—	V _{CCIO} /2 + 0.15
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO}	V _{CCIO} /2 - 0.175	—	V _{CCIO} /2 + 0.175	0.5	V _{CCIO}	V _{CCIO} /2 - 0.125	—	V _{CCIO} /2 + 0.125
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	V _{CCIO} /2	—	0.35	—	—	V _{CCIO} /2	—

Table 1–29 lists the differential SSTL I/O standards for Arria II GZ devices

Table 1–29. Differential SSTL I/O Standards for Arria II GZ Devices

I/O Standard	V _{CCIO} (V)			V _{SWING(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)		V _{OX(AC)} (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.2	—	V _{CCIO} /2 + 0.2	0.62	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.15	—	V _{CCIO} /2 + 0.15
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.175	—	V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.125	—	V _{CCIO} /2 + 0.125
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	V _{CCIO} /2	—	0.35	—	—	V _{CCIO} /2	—

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 3 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit		
		Min	Typ	Max	Min	Typ	Max			
Receiver DC Coupling Support	—	For more information about receiver DC coupling support, refer to the “DC-Coupled Links” section in the <i>Transceiver Architecture for Arria II Devices</i> chapter.						—		
Differential on-chip termination resistors	85- Ω setting	85 \pm 20%		85 \pm 20%		Ω		Ω		
	100- Ω setting	100 \pm 20%		100 \pm 20%		Ω				
	120- Ω setting	120 \pm 20%		120 \pm 20%		Ω				
	150- Ω setting	150 \pm 20%		150 \pm 20%		Ω				
Differential and common mode return loss	PCIe (Gen 1 and Gen 2), XAUI, HiGig+, CEI SR/LR, SRIO SR/LR, CPRI LV/HV, OBSAI, SATA	Compliant						—		
Programmable PPM detector (9)	—	\pm 62.5, 100, 125, 200, 250, 300, 500, 1,000						ppm		
Run length	—	—	—	200	—	—	200	UI		
Programmable equalization	—	—	—	16	—	—	16	dB		
t _{LTR} (10)	—	—	—	75	—	—	75	μ s		
t _{LTD_Manual} (11)	—	15	—	—	15	—	—	μ s		
t _{LTD_Manual} (12)	—	—	—	4000	—	—	4000	ns		
t _{LTD_Auto} (13)	—	—	—	4000	—	—	4000	ns		
Receiver CDR 3 dB Bandwidth in lock-to-data (LTD) mode	PCIe Gen1	2.0 - 3.5						MHz		
	PCIe Gen2	40 - 65						MHz		
	(OIF) CEI PHY at 6.375 Gbps	20 - 35						MHz		
	XAUI	10 - 18						MHz		
	SRIO 1.25 Gbps	10 - 18						MHz		
	SRIO 2.5 Gbps	10 - 18						MHz		
	SRIO 3.125 Gbps	6 - 10						MHz		
	GIGE	6 - 10						MHz		
	SONET OC12	3 - 6						MHz		
	SONET OC48	14 - 19						MHz		
Receiver buffer and CDR offset cancellation time (per channel)	—	—	—	17000	—	—	17000	recon fig_clk cycles		
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	dB		
	DC Gain Setting = 1	—	3	—	—	3	—	dB		
	DC Gain Setting = 2	—	6	—	—	6	—	dB		

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 4 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit		
		Min	Typ	Max	Min	Typ	Max			
Transmitter										
Supported I/O Standards		1.5-V PCML								
Data rate (14)	—	600	—	6375	600	—	3750	Mbps		
V _{OCM}	0.65 V setting	—	650	—	—	650	—	mV		
Differential on-chip termination resistors	85-Ω setting	85 ± 15%			85 ± 15%			Ω		
	100-Ω setting	100 ± 15%			100 ± 15%			Ω		
	120-Ω setting	120 ± 15%			120 ± 15%			Ω		
	150-Ω setting	150 ± 15%			150 ± 15%			Ω		
Differential and common mode return loss	PCIe Gen1 and Gen2 (TX V _{OD} =4), XAUI (TX V _{OD} =6), HiGig+ (TX V _{OD} =6), CEI SR/LR (TX V _{OD} =8), SRIO SR (V _{OD} =6), SRIO LR (V _{OD} =8), CPRI LV (V _{OD} =6), CPRI HV (V _{OD} =2), OBSAI (V _{OD} =6), SATA (V _{OD} =4),	Compliant								
Rise time (15)	—	50	—	200	50	—	200	ps		
Fall time (15)	—	50	—	200	50	—	200	ps		
Intra-differential pair skew	—	—	—	15	—	—	15	ps		
Intra-transceiver block transmitter channel-to-channel skew	×4 PMA and PCS bonded mode Example: XAUI, PCIe ×4, Basic ×4	—	—	120	—	—	120	ps		
Inter-transceiver block transmitter channel-to-channel skew	×8 PMA and PCS bonded mode Example: PCIe ×8, Basic ×8	—	—	500	—	—	500	ps		
CMU0 PLL and CMU1 PLL										
Supported Data Range	—	600	—	6375	600	—	3750	Mbps		
p11_powerdown minimum pulse width (tp11_powerdown)	—	1			1			μs		
CMU PLL lock time from p11_powerdown de-assertion	—	—	—	100	—	—	100	μs		

Table 1–37 lists the typical V_{OD} for TX term that equals $100\ \Omega$ for Arria II GX and GZ devices.

Table 1–37. Typical V_{OD} Setting, TX Termination = $100\ \Omega$ for Arria II Devices

Quartus II Setting	V_{OD} Setting (mV)
1	400
2	600
3 (Arria II GZ)	700
4	800
5	900
6	1000
7	1200

Table 1–38 lists the typical transmitter pre-emphasis levels in dB for the first post tap under the following conditions: low-frequency data pattern (five 1s and five 0s) at 6.375 Gbps. The levels listed in Table 1–38 are a representation of possible pre-emphasis levels under these specified conditions only; the pre-emphasis levels may change with data pattern and data rate.

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Arria II GX HSSI HSPICE models.

Table 1–38. Transmitter Pre-Emphasis Levels for Arria II GX Devices

Arria II GX (Quartus II Software) First Post Tap Setting	Arria II GX (Quartus II Software) V_{OD} Setting						
	1	2	4	5	6	7	Unit
0 (off)	0	0	0	0	0	0	—
1	0.7	0	0	0	0	0	dB
2	2.7	1.2	0.3	0	0	0	dB
3	4.9	2.4	1.2	0.8	0.5	0.2	dB
4	7.5	3.8	2.1	1.6	1.2	0.6	dB
5	—	5.3	3.1	2.4	1.8	1.1	dB
6	—	7	4.3	3.3	2.7	1.7	dB

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 3 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max										
PCIe Receiver Jitter Tolerance (4)														
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			> 0.6			> 0.6			UI
PCIe (Gen 1) Electrical Idle Detect Threshold (9)														
VRX-IDLE-DETDIFF (p-p)	Compliance pattern	65	—	175	65	—	175	65	—	175	65	—	175	mV
Serial RapidIO® (SRIO) Transmit Jitter Generation (5)														
Deterministic jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
Total jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
SRIO Receiver Jitter Tolerance (5)														
Deterministic jitter tolerance (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 1.875 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
	Jitter frequency = 20 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
GIGE Transmit Jitter Generation (6)														
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	—	—	0.14	—	—	0.14	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 2 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Jitter tolerance at 2488.32 Mbps	Jitter frequency = 0.06 KHz Pattern = PRBS15	> 15		> 15		> 15		UI
	Jitter frequency = 100 KHZ Pattern = PRBS15	> 1.5		> 1.5		> 1.5		UI
	Jitter frequency = 1 MHz Pattern = PRBS15	> 0.15		> 0.15		> 0.15		UI
	Jitter frequency = 10 MHz Pattern = PRBS15	> 0.15		> 0.15		> 0.15		UI
Fibre Channel Transmit Jitter Generation (4), (5)								
Total jitter FC-1	Pattern = CRPAT	—	—	0.23	—	—	0.23	UI
Deterministic jitter FC-1	Pattern = CRPAT	—	—	0.11	—	—	0.11	UI
Total jitter FC-2	Pattern = CRPAT	—	—	0.33	—	—	0.33	UI
Deterministic jitter FC-2	Pattern = CRPAT	—	—	0.2	—	—	0.2	UI
Total jitter FC-4	Pattern = CRPAT	—	—	0.52	—	—	0.52	UI
Deterministic jitter FC-4	Pattern = CRPAT	—	—	0.33	—	—	0.33	UI
Fibre Channel Receiver Jitter Tolerance (4), (6)								
Deterministic jitter FC-1	Pattern = CJTPAT	> 0.37		> 0.37		> 0.37		UI
Random jitter FC-1	Pattern = CJTPAT	> 0.31		> 0.31		> 0.31		UI
Sinusoidal jitter FC-1	Fc/25000	> 1.5		> 1.5		> 1.5		UI
	Fc/1667	> 0.1		> 0.1		> 0.1		UI
Deterministic jitter FC-2	Pattern = CJTPAT	> 0.33		> 0.33		> 0.33		UI
Random jitter FC-2	Pattern = CJTPAT	> 0.29		> 0.29		> 0.29		UI
Sinusoidal jitter FC-2	Fc/25000	> 1.5		> 1.5		> 1.5		UI
	Fc/1667	> 0.1		> 0.1		> 0.1		UI
Deterministic jitter FC-4	Pattern = CJTPAT	> 0.33		> 0.33		> 0.33		UI
Random jitter FC-4	Pattern = CJTPAT	> 0.29		> 0.29		> 0.29		UI
Sinusoidal jitter FC-4	Fc/25000	> 1.5		> 1.5		> 1.5		UI
	Fc/1667	> 0.1		> 0.1		> 0.1		UI
XAU1 Transmit Jitter Generation (7)								
Total jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.3	—	—	0.3	UI
Deterministic jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
XAU1 Receiver Jitter Tolerance (7)								
Total jitter	—	> 0.65		> 0.65		> 0.65		UI
Deterministic jitter	—	> 0.37		> 0.37		> 0.37		UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 3 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Peak-to-peak jitter	Jitter frequency = 22.1 KHz	> 8.5			> 8.5			UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz	> 0.1			> 0.1			UI
Peak-to-peak jitter	Jitter frequency = 20 MHz	> 0.1			> 0.1			UI
PCIe Transmit Jitter Generation (8)								
Total jitter at 2.5 Gbps (Gen1)—x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	0.25	UI
Total jitter at 5 Gbps (Gen2)—x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	—	UI
PCIe Receiver Jitter Tolerance (8)								
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			UI
Total jitter at 5 Gbps (Gen2)	Compliance pattern	Not supported			Not supported			UI
PCIe (Gen 1) Electrical Idle Detect Threshold								
V _{RX-IDLE-DETDIFFp-p} (9)	Compliance pattern	65	—	175	65	—	175	UI
SRIO Transmit Jitter Generation (10)								
Deterministic jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
Total jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
SRIO Receiver Jitter Tolerance (10)								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.55			> 0.55			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 1.875 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
	Jitter frequency = 20 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
GIGE Transmit Jitter Generation (11)								
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	UI
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.279	—	—	0.279	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 4 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
GIGE Receiver Jitter Tolerance (11)								
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT			> 0.4			> 0.4	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT			> 0.66			> 0.66	UI
HiGig Transmit Jitter Generation								
Deterministic jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.17	—	—	—	UI
Total jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.35	—	—	—	UI
HiGig Receiver Jitter Tolerance								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT			> 0.37	—	—	—	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT			> 0.65	—	—	—	UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT			> 8.5	—	—	—	UI
	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT			> 0.1	—	—	—	UI
	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT			> 0.1	—	—	—	UI
(OIF) CEI Transmitter Jitter Generation								
Total jitter (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS15 BER = 10^{-12}	—	—	0.3	—	—	0.3	UI
(OIF) CEI Receiver Jitter Tolerance								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10^{-12}			> 0.675	—	—	—	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10^{-12}			> 0.988	—	—	—	UI

Core Performance Specifications for the Arria II Device Family

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), embedded memory, configuration, and JTAG specifications for Arria II GX and GZ devices.

Clock Tree Specifications

Table 1–42 lists the clock tree specifications for Arria II GX devices.

Table 1–42. Clock Tree Performance for Arria II GX Devices

Clock Network	Performance			Unit
	I3, C4	C5,I5	C6	
GCLK and RCLK	500	500	400	MHz
PCLK	420	350	280	MHz

Table 1–43 lists the clock tree specifications for Arria II GZ devices.

Table 1–43. Clock Tree Performance for Arria II GZ Devices

Clock Network	Performance		Unit
	-C3 and -I3	-C4 and -I4	
GCLK and RCLK	700	500	MHz
PCLK	500	450	MHz

PLL Specifications

Table 1–44 lists the PLL specifications for Arria II GX devices.

Table 1–44. PLL Specifications for Arria II GX Devices (Part 1 of 3)

Symbol	Description	Min	Typ	Max	Unit
f_{IN}	Input clock frequency (from clock input pins residing in right/top/bottom banks) (-4 Speed Grade)	5	—	670 (1)	MHz
	Input clock frequency (from clock input pins residing in right/top/bottom banks) (-5 Speed Grade)	5	—	622 (1)	MHz
	Input clock frequency (from clock input pins residing in right/top/bottom banks) (-6 Speed Grade)	5	—	500 (1)	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{VCO}	PLL VCO operating Range (2)	600	—	1,400	MHz
f_{INDUTY}	Input clock duty cycle	40	—	60	%
$f_{EINDUTY}$	External feedback clock input duty cycle	40	—	60	%
t_{INCCJ} (3), (4)	Input clock cycle-to-cycle jitter (Frequency \geq 100 MHz)	—	—	0.15	UI (p–p)
	Input clock cycle-to-cycle jitter (Frequency \leq 100 MHz)	—	—	± 750	ps (p–p)

Table 1–53. High-Speed I/O Specifications for Arria II GX Devices (Part 4 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(3)	945 (7)	(3)	945 (7)	(3)	740 (7)	(3)	640 (7)	Mbps
	SERDES factor J = 2 (using DDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
	SERDES factor J = 1 (using SDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
Soft-CDR PPM tolerance	Soft-CDR mode	—	300	—	300	—	300	—	300	\pm PPM
DPA run length	DPA mode	—	10,000	—	10,000	—	10,000	—	10,000	UI
Sampling window (SW)	Non-DPA mode (5)	—	300	—	300	—	350	—	400	ps

Notes to Table 1–53:

- (1) $f_{HSCLK_IN} = f_{HSDR} / W$. Use W to determine the supported selection of input reference clock frequencies for the desired data rate.
- (2) Applicable for interfacing with DPA receivers only. For interfacing with non-DPA receivers, you must calculate the leftover timing margin in the receiver by performing link timing closure analysis. For Arria II GX transmitter to Arria II GX non-DPA receiver, the maximum supported data rate is 945 Mbps. For data rates above 840 Mbps, perform PCB trace compensation by adjusting the PCB trace length for LVDS channels to improve channel-to-channel skews.
- (3) The minimum and maximum specification depends on the clock source (for example, PLL and clock pin) and the clock routing resource you use (global, regional, or local). The I/O differential buffer and input register do not have a minimum toggle rate.
- (4) The specification is only applicable under the influence of core noise.
- (5) Applicable for true LVDS using dedicated SERDES only.
- (6) Dedicated SERDES and DPA features are only available on the right banks.
- (7) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and the receiver sampling margin to determine the leftover timing margin.

Table 1–54 lists the high-speed I/O timing for Arria II GZ devices.

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 1 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Clock								
f_{HSCLK_in} (input clock frequency) true differential I/O standards	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f_{HSCLK_in} (input clock frequency) single ended I/O standards (9)	Clock boost factor W = 1 to 40 (3)	5	—	717	5	—	717	MHz
f_{HSCLK_in} (input clock frequency) single ended I/O standards (10)	Clock boost factor W = 1 to 40 (3)	5	—	420	5	—	420	MHz

Figure 1–6 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Figure 1–6. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for Arria II GZ Devices at a 1.25 Gbps Data Rate

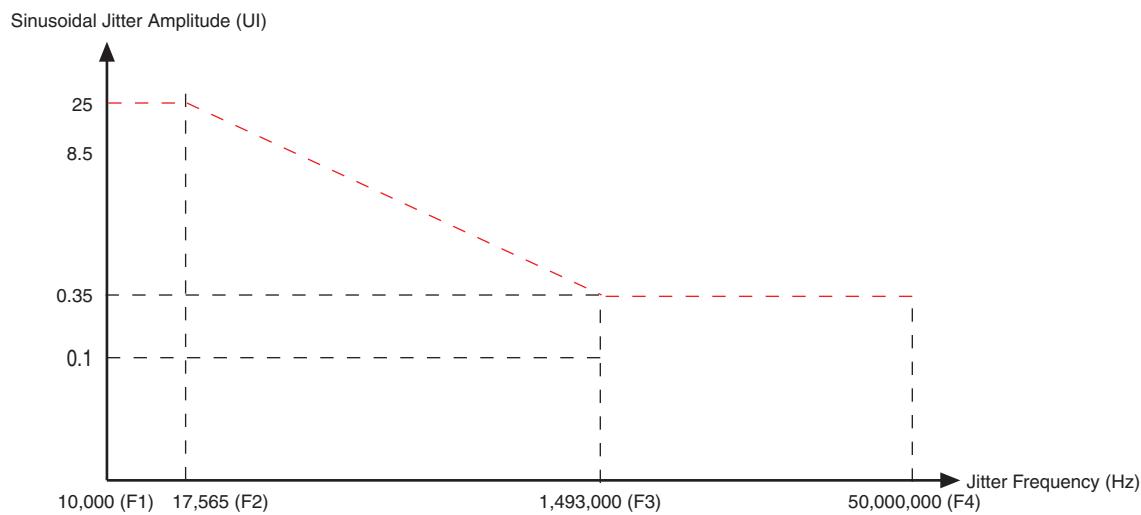


Table 1–56 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Table 1–56. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for Arria II GZ Devices at 1.25 Gbps Data Rate

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

External Memory Interface Specifications

For the maximum clock rate supported for Arria II GX and GZ device family, refer to the [External Memory Interface Spec Estimator](#) page on the Altera website.

Table 1–57 lists the external memory interface specifications for Arria II GX devices.

Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 1 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
0	90-140	90-130	90-110	22.5	Low	16
1	110-180	110-170	110-150	30	Low	12
2	140-220	140-210	140-180	36	Low	10
3	170-270	170-260	170-220	45	Low	8
4	220-340	220-310	220-270	30	High	12

Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1–57:

- (1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1–58. DLL Frequency Range Specifications for Arria II GZ Devices

Frequency Mode	Frequency Range (MHz)		Available Phase Shift	DQS Delay Buffer Mode (1)	Number of Delay Chains
	-3	-4			
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°, 135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1–58:

- (1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1–59. DQS Phase Offset Delay Per Setting for Arria II GX Devices (Note 1), (2), (3)

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1–59:

- (1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.
(2) The typical value equals the average of the minimum and maximum values.
(3) The delay settings are linear.

Table 1–60 lists the DQS phase shift error for Arria II GX devices.

Table 1–60. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria II GX Devices (Note 1)

Number of DQS Delay Buffer	C4	I3, C5, I5	C6	Unit
1	26	30	36	ps
2	52	60	72	ps
3	78	90	108	ps
4	104	120	144	ps

Note to Table 1–60:

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a C4 speed grade is ± 78 ps or ± 39 ps.

Table 1–61 lists the DQS phase shift error for Arria II GZ devices.

Table 1–61. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria II GZ Devices (Note 1)

Number of DQS Delay Buffer	-3	-4	Unit
1	28	30	ps
2	56	60	ps
3	84	90	ps
4	112	120	ps

Note to Table 1–61:

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a 3 speed grade is ± 84 ps or ± 42 ps.

Table 1–62 lists the memory output clock jitter specifications for Arria II GX devices.

Table 1–62. Memory Output Clock Jitter Specification for Arria II GX Devices (Note 1), (2), (3)

Parameter	Clock Network	Symbol	-4		-5		-6		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	Global	$t_{JIT(per)}$	-100	100	-125	125	-125	125	ps
Cycle-to-cycle period jitter	Global	$t_{JIT(cc)}$	-200	200	-250	250	-250	250	ps
Duty cycle jitter	Global	$t_{JIT(duty)}$	-100	100	-125	125	-125	125	ps

Notes to Table 1–62:

- (1) The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.
(2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock network.
(3) The memory output clock jitter stated in Table 1–62 is applicable when an input jitter of 30 ps is applied.

I/O Timing

Altera offers two ways to determine I/O timing:

- Using the Microsoft Excel-based I/O Timing.
- Using the Quartus II Timing Analyzer.

The Microsoft Excel-based I/O Timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II timing analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after place-and-route is complete.



The Microsoft Excel-based I/O Timing spreadsheet is downloadable from the [Literature: Arria II Devices](#) web page.

Glossary

Table 1–68 lists the glossary for this chapter.

Table 1–68. Glossary (Part 1 of 4)

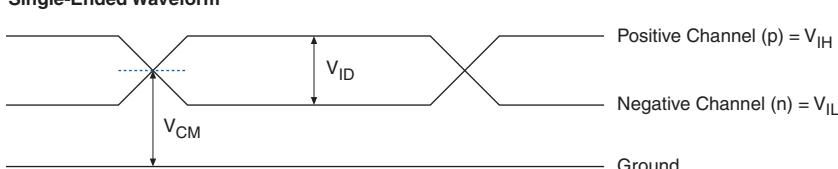
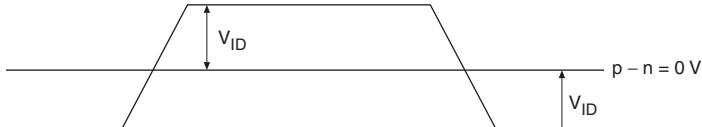
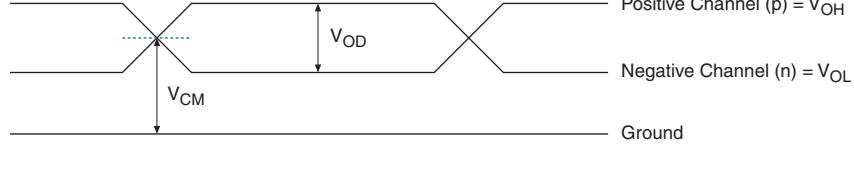
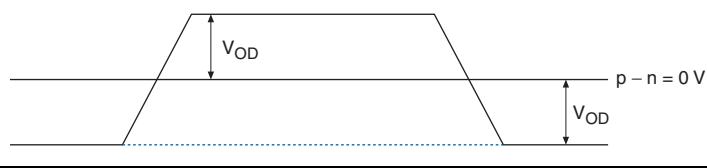
Letter	Subject	Definitions
	Differential I/O Standards	<p><i>Receiver Input Waveforms</i></p> <p>Single-Ended Waveform</p>  <p>Positive Channel (p) = V_{IH} Negative Channel (n) = V_{IL} Ground V_{CM} V_{ID}</p> <p>Differential Waveform</p>  <p>$p - n = 0\text{ V}$ V_{ID}</p> <p><i>Transmitter Output Waveforms</i></p> <p>Single-Ended Waveform</p>  <p>Positive Channel (p) = V_{OH} Negative Channel (n) = V_{OL} Ground V_{CM} V_{OD}</p> <p>Differential Waveform</p>  <p>$p - n = 0\text{ V}$ V_{OD}</p>
E, F	f_{HSCLK}	Left/Right PLL input clock frequency.
	f_{HSDR}	High-speed I/O block: Maximum/minimum LVDS data transfer rate ($f_{HSDR} = 1/\text{TUI}$), non-DPA.
	$f_{HSDRDPA}$	High-speed I/O block: Maximum/minimum LVDS data transfer rate ($f_{HSDRDPA} = 1/\text{TUI}$), DPA.

Table 1–68. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G, H, I, J	J JTAG Timing Specifications	<p>High-speed I/O block: Deserialization factor (width of parallel data bus).</p> <p>JTAG Timing Specifications:</p> <p>The diagram illustrates the timing sequence for JTAG operations. It shows four signals: TMS, TDI, TCK, and TDO. TMS and TDI are high-speed parallel data buses. TCK is a clock signal. TDO is a low-speed parallel data bus. Various timing parameters are labeled: t_{JCP} (TMS setup time), t_{JCH} (TMS hold time), t_{JCL} (TDI setup time), t_{JPSU} (TDI hold time), t_{JPH} (TDO hold time), t_{JPZX} (TDO setup time), t_{JPZO} (TDO hold time), and t_{JPXZ} (TDO output time).</p>
K, L, M, N, O, P	PLL Specifications	<p>PLL Specification parameters:</p> <p>Diagram of PLL Specifications (1)</p> <p>The diagram shows a detailed block diagram of a PLL. It includes a Core Clock input, a Synchronizer, a Phase Frequency Detector (PFD), a Charge Pump (CP), a Loop Filter (LF), a Voltage Controlled Oscillator (VCO), a VCO post-scale counter K (with a value of 2), a Counter CO.C9, and various output paths for CLKOUT pins, GCLK, and RCLK. A feedback path from the output is labeled "External Feedback". A key legend indicates that blue boxes represent "Reconfigurable in User Mode".</p> <p>Notes:</p> <ul style="list-style-type: none"> (1) CoreClock can only be fed by dedicated clock input pins or PLL outputs. (2) This is the VCO post-scale counter K.
Q, R	R_L	Receiver differential input discrete resistor (external to the Arria II device).

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	<ul style="list-style-type: none"> ■ Updated the $V_{CCH_GXBL/R}$ operating conditions in Table 1–6. ■ Finalized Arria II GZ information in Table 1–20. ■ Added BLVDS specification in Table 1–32 and Table 1–33. ■ Updated input and output waveforms in Table 1–68.
December 2011	4.2	<ul style="list-style-type: none"> ■ Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. ■ Minor text edits.
June 2011	4.1	<ul style="list-style-type: none"> ■ Added Table 1–60. ■ Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. ■ Updated the “Switching Characteristics” section introduction. ■ Minor text edits.